

# DZ2J027

## Silicon epitaxial planar type

For constant voltage / waveform clipper and surge absorption circuit

Low noise type

### ■ Features

- Excellent rising characteristics of zener current  $I_Z$
- Low zener operating resistance  $R_Z$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Package

- Code  
SMini2-F5-B
- Pin Name  
1. Cathode  
2. Anode

### ■ Marking Symbol: 2J, 2U

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	$I_{FRM}$	200	mA
Total power dissipation *	$P_T$	200	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $P_T = 200$  mW achieved with a printed circuit board.

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 10$ mA			1.0	V
Zener voltage *1,2,4	$V_Z$	$I_Z = 5$ mA	2.57		2.84	V
Zener operating resistance	$R_Z$	$I_Z = 5$ mA			110	$\Omega$
Reverse current	$I_R$	$V_R = 1$ V			120	$\mu\text{A}$
Temperature coefficient of zener voltage *3	$S_Z$	$I_Z = 5$ mA		-1.9		mV/ $^\circ\text{C}$

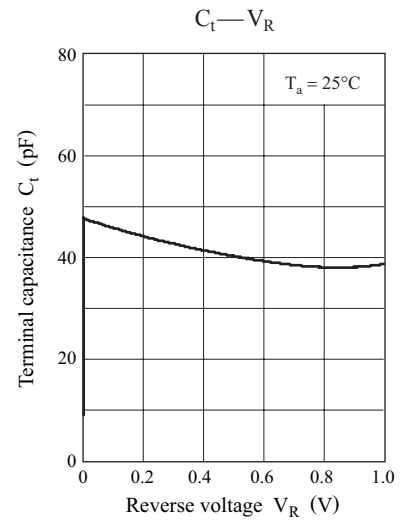
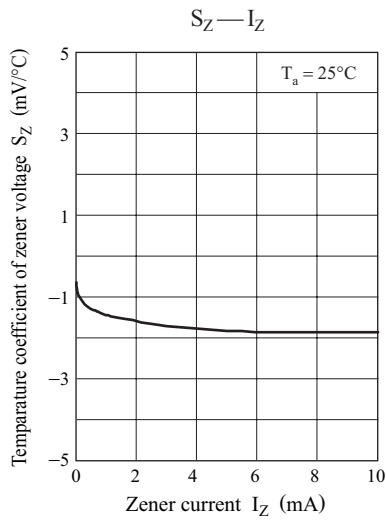
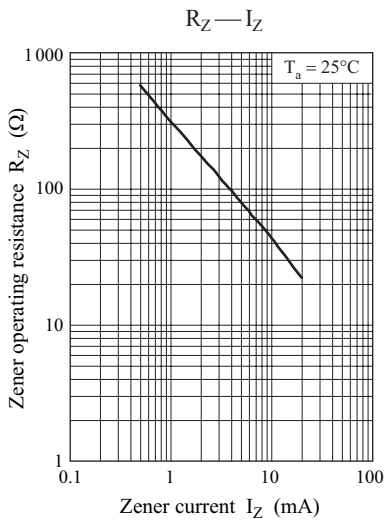
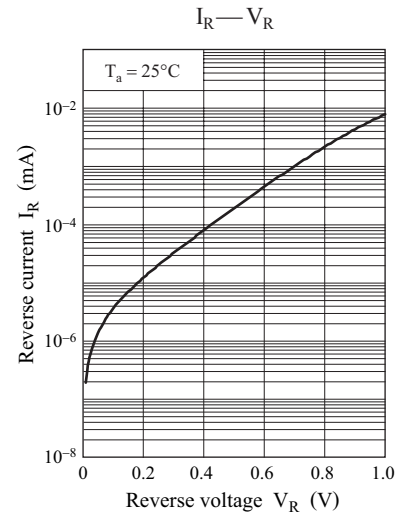
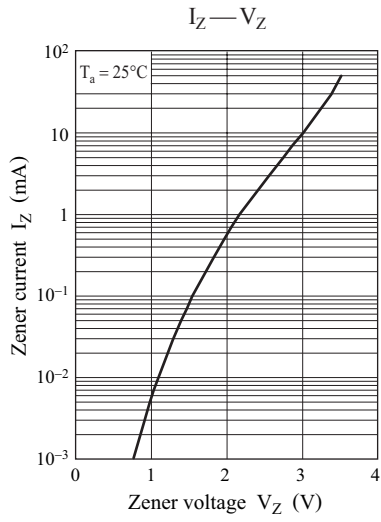
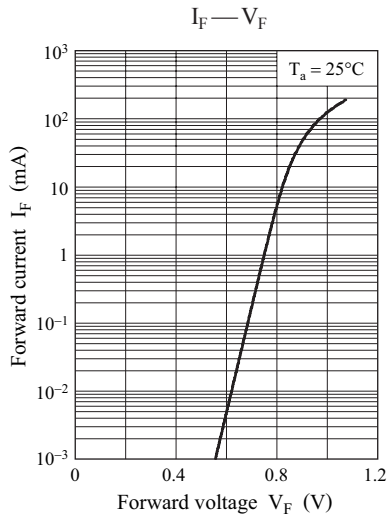
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

3. \*1: The temperature must be controlled  $25^\circ\text{C}$  for  $V_Z$  measurement.  $V_Z$  value measured at other temperature must be adjusted to  $V_Z (25^\circ\text{C})$ \*2:  $V_Z$  guaranteed 20 ms after current flow.\*3:  $T_j = 25^\circ\text{C}$  to  $150^\circ\text{C}$ 

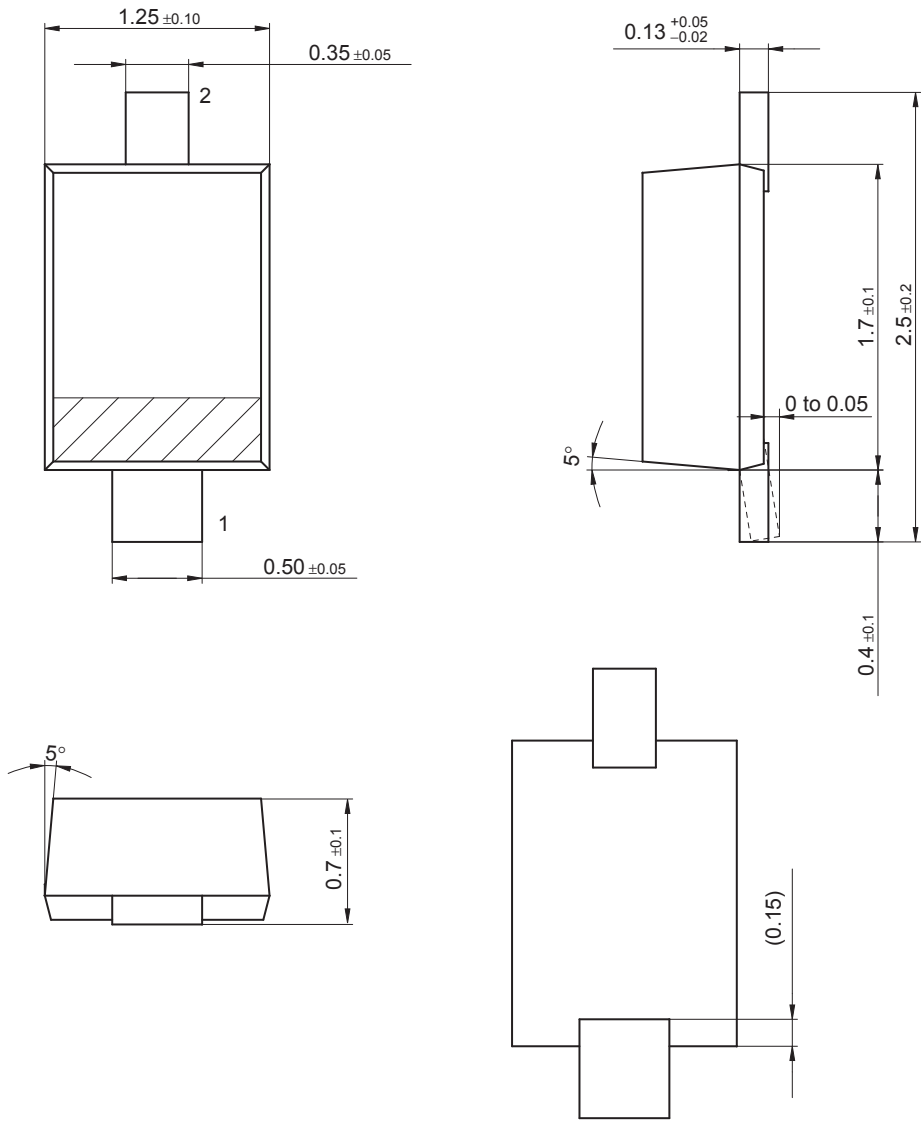
\*4: Rank classification

Code	M	0
Rank	M	No-rank
$V_Z$	2.63 to 2.77	2.57 to 2.84
Marking Symbol	2U	2J



SMini2-F5-B

Unit: mm



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